

MEG00-001

Serial number 09/684,519

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TO: COMMISSIONER OF PATENTS AND TRADEMARKS  
Washington, D.C. 20231

From : George O. Saile (Reg. No. 19,572)  
20 McIntosh Drive  
Poughkeepsie, NY 12603



Date: April 15, 2002

REF: APPLICANT : Jin-Yuan Lee  
~~SERIAL NO.~~ : 09/684,519  
~~ART UNIT~~ : 2841  
FILING DATE : 10/10/00  
ATT'Y NO. : MEG01-001  
EXAMINER : Bui, Hung S.  
TITLE : A THERMALLY COMPLIANT PCB  
SUBSTRATE FOR THE APPLICATION  
OF CHIP SCALE PACKAGES.

#7/Fwd. of  
Tne(2)Response  
R. Yuen  
8/22/02  
RECEIVED  
AUG 20 2002  
TECHNOLOGY CENTER 2800

AMENDMENT AND RESPONSE TO OFFICE ACTION

Sir:

In response to an office action mailed on 02/28/02  
please consider the following amendments and remarks with  
respect to the above referenced application.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal service as First  
Class mail in an envelop addressed to the Commissioner of  
Patents and Trademarks, Washington, D.C. 20231, on  
July 29, 2002.

George O. Saile (Reg. No 19,572)

 7/29/02

Signature

Date

08/07/2002 RAHMED: 00000029 190033 09694515

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